

# 74LVC2G06

## Inverters with open-drain outputs

Rev. 6 — 4 July 2012

Product data sheet

## 1. General description

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The 74LVC2G06 provides two inverting buffers.

The output of this device is an open drain and can be connected to other open-drain outputs to implement active-LOW wired-OR or active-HIGH wired-AND functions.

Input can be driven from either 3.3 V or 5 V devices. This feature allows the use of this device in a mixed 3.3 V and 5 V environment.

Schmitt trigger action at all inputs makes the circuit tolerant for slower input rise and fall time.

This device is fully specified for partial power-down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

## 2. Features and benefits

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- Wide supply voltage range from 1.65 V to 5.5 V
- 5 V tolerant input/output for interfacing with 5 V logic
- High noise immunity
- Complies with JEDEC standard:
  - ◆ JESD8-7 (1.65 V to 1.95 V)
  - ◆ JESD8-5 (2.3 V to 2.7 V)
  - ◆ JESD8-B/JESD36 (2.7 V to 3.6 V)
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- -24 mA output drive ( $V_{CC} = 3.0$  V)
- CMOS low power consumption
- Latch-up performance exceeds 250 mA
- Direct interface with TTL levels
- Inputs accept voltages up to 5 V
- Multiple package options
- Specified from -40 °C to +85 °C and -40 °C to +125 °C



3. Ordering information

Table 1. Ordering information

| Type number | Package           |       |   |         |
|-------------|-------------------|-------|---|---------|
|             | Temperature range | Name  | Description   | Version |
| 74LVC2G06GW | −40 °C to +125 °C | SC-88 | plastic surface-mounted package; 6 leads  | SOT363  |
| 74LVC2G06GV | −40 °C to +125 °C | TSOP6 | plastic surface-mounted package (TSOP6); 6 leads  | SOT457  |
| 74LVC2G06GM | −40 °C to +125 °C | XSON6 | plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm | SOT886  |
| 74LVC2G06GF | −40 °C to +125 °C | XSON6 | plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1 × 0.5 mm    | SOT891  |
| 74LVC2G06GN | −40 °C to +125 °C | XSON6 | extremely thin small outline package; no leads; 6 terminals; body 0.9 × 1.0 × 0.35 mm       | SOT1115 |
| 74LVC2G06GS | −40 °C to +125 °C | XSON6 | extremely thin small outline package; no leads; 6 terminals; body 1.0 × 1.0 × 0.35 mm       | SOT1202 |

4. Marking

Table 2. Marking

| Type number | Marking code <sup>[1]</sup> |
|-------------|-----------------------------|
| 74LVC2G06GW | V6                          |
| 74LVC2G06GV | V06                         |
| 74LVC2G06GM | V6                          |
| 74LVC2G06GF | V6                          |
| 74LVC2G06GN | V6                          |
| 74LVC2G06GS | V6                          |

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram

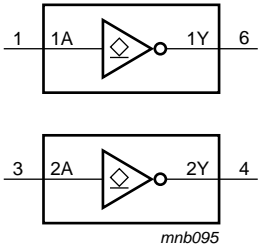


Fig 1. Logic symbol

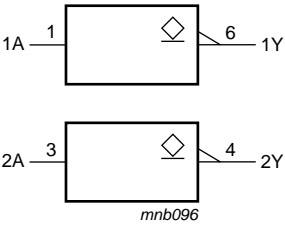


Fig 2. IEC logic symbol

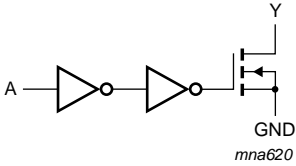


Fig 3. Logic diagram (one driver)

## 6. Pinning information

### 6.1 Pinning

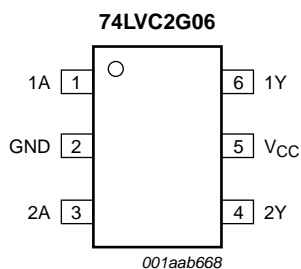


Fig 4. Pin configuration SOT363 and SOT457

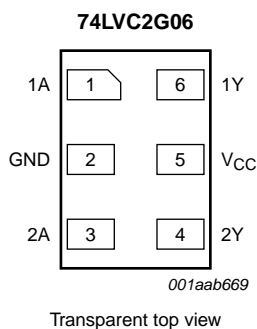


Fig 5. Pin configuration SOT886

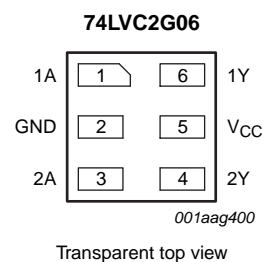


Fig 6. Pin configuration SOT891, SOT1115 and SOT1202

### 6.2 Pin description

Table 3. Pin description

| Symbol          | Pin | Description    |
|-----------------|-----|----------------|
| 1A              | 1   | data input     |
| GND             | 2   | ground (0 V)   |
| 2A              | 3   | data input     |
| 2Y              | 4   | data output    |
| V <sub>CC</sub> | 5   | supply voltage |
| 1Y              | 6   | data output    |

## 7. Functional description

Table 4. Function table<sup>[1]</sup>

| Input nA | Output nY |
|----------|-----------|
| L        | Z         |
| H        | L         |

[1] H = HIGH voltage level; L = LOW voltage level; Z = high-impedance OFF-state.

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol          | Parameter              | Conditions           | Min                 | Max  | Unit |
|-----------------|------------------------|----------------------|---------------------|------|------|
| V <sub>CC</sub> | supply voltage         |                      | -0.5                | +6.5 | V    |
| I <sub>IK</sub> | input clamping current | V <sub>I</sub> < 0 V | -50                 | -    | mA   |
| V <sub>I</sub>  | input voltage          |                      | <sup>[1]</sup> -0.5 | +6.5 | V    |

**Table 5.** Limiting values ...continued

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol    | Parameter               | Conditions                    | Min         | Max  | Unit |
|-----------|-------------------------|-------------------------------|-------------|------|------|
| $I_{OK}$  | output clamping current | $V_O < 0$ V                   | -50         | -    | mA   |
| $V_O$     | output voltage          | Active mode                   | [1] -0.5    | +6.5 | V    |
|           |                         | Power-down mode               | [1][2] -0.5 | +6.5 | V    |
| $I_O$     | output current          | $V_O = 0$ V to 6.5 V          | -           | 50   | mA   |
| $I_{CC}$  | supply current          |                               | -           | 100  | mA   |
| $I_{GND}$ | ground current          |                               | -100        | -    | mA   |
| $T_{stg}$ | storage temperature     |                               | -65         | +150 | °C   |
| $P_{tot}$ | total power dissipation | $T_{amb} = -40$ °C to +125 °C | [3] -       | 250  | mW   |

[1] The minimum input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] When  $V_{CC} = 0$  V (Power-down mode), the output voltage can be 5.5 V in normal operation.

[3] For SC-88 and SC-74 packages: above 87.5 °C the value of  $P_{tot}$  derates linearly with 4.0 mW/K.  
For XSON6 packages: above 118 °C the value of  $P_{tot}$  derates linearly with 7.8 mW/K.

## 9. Recommended operating conditions

**Table 6.** Recommended operating conditions

| Symbol              | Parameter                           | Conditions                      | Min  | Typ | Max  | Unit |
|---------------------|-------------------------------------|---------------------------------|------|-----|------|------|
| $V_{CC}$            | supply voltage                      |                                 | 1.65 | -   | 5.5  | V    |
| $V_I$               | input voltage                       |                                 | 0    | -   | 5.5  | V    |
| $V_O$               | output voltage                      | Active mode                     | 0    | -   | 5.5  | V    |
|                     |                                     | Power-down mode; $V_{CC} = 0$ V | 0    | -   | 5.5  | V    |
| $T_{amb}$           | ambient temperature                 |                                 | -40  | -   | +125 | °C   |
| $\Delta t/\Delta V$ | input transition rise and fall rate | $V_{CC} = 1.65$ V to 2.7 V      | -    | -   | 20   | ns/V |
|                     |                                     | $V_{CC} = 2.7$ V to 5.5 V       | -    | -   | 10   | ns/V |

## 10. Static characteristics

**Table 7. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol                                    | Parameter                 | Conditions  | Min                    | Typ <sup>[1]</sup> | Max                    | Unit |
|---|---------------------------|---|------------------------|--------------------|------------------------|------|
| <b>T<sub>amb</sub> = -40 °C to +85 °C</b> |                           |   |                        |                    |                        |      |
| V <sub>IH</sub>                           | HIGH-level input voltage  | V <sub>CC</sub> = 1.65 V to 1.95 V  | 0.65 × V <sub>CC</sub> | -                  | -                      | V    |
|   |                           | V <sub>CC</sub> = 2.3 V to 2.7 V  | 1.7                    | -                  | -                      | V    |
|   |                           | V <sub>CC</sub> = 2.7 V to 3.6 V  | 2.0                    | -                  | -                      | V    |
|   |                           | V <sub>CC</sub> = 4.5 V to 5.5 V  | 0.7 × V <sub>CC</sub>  | -                  | -                      | V    |
| V <sub>IL</sub>                           | LOW-level input voltage   | V <sub>CC</sub> = 1.65 V to 1.95 V  | -                      | -                  | 0.35 × V <sub>CC</sub> | V    |
|   |                           | V <sub>CC</sub> = 2.3 V to 2.7 V  | -                      | -                  | 0.7                    | V    |
|   |                           | V <sub>CC</sub> = 2.7 V to 3.6 V  | -                      | -                  | 0.8                    | V    |
|   |                           | V <sub>CC</sub> = 4.5 V to 5.5 V  | -                      | -                  | 0.3 × V <sub>CC</sub>  | V    |
| V <sub>OL</sub>                           | LOW-level output voltage  | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>   |                        |                    |                        |      |
|   |                           | I <sub>O</sub> = 100 μA; V <sub>CC</sub> = 1.65 V to 5.5 V  | -                      | -                  | 0.1                    | V    |
|   |                           | I <sub>O</sub> = 4 mA; V <sub>CC</sub> = 1.65 V   | -                      | -                  | 0.45                   | V    |
|   |                           | I <sub>O</sub> = 8 mA; V <sub>CC</sub> = 2.3 V  | -                      | -                  | 0.3                    | V    |
|   |                           | I <sub>O</sub> = 12 mA; V <sub>CC</sub> = 2.7 V   | -                      | -                  | 0.4                    | V    |
|   |                           | I <sub>O</sub> = 24 mA; V <sub>CC</sub> = 3.0 V   | -                      | -                  | 0.55                   | V    |
|   |                           | I <sub>O</sub> = 32 mA; V <sub>CC</sub> = 4.5 V   | -                      | -                  | 0.55                   | V    |
| I <sub>I</sub>                            | input leakage current     | V <sub>I</sub> = 5.5 V or GND;<br>V <sub>CC</sub> = 0 V to 5.5 V  | <sup>[2]</sup> -       | ±0.1               | ±5                     | μA   |
| I <sub>OZ</sub>                           | OFF-state output current  | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND;<br>V <sub>CC</sub> = 5.5 V | -                      | ±0.1               | ±10                    | μA   |
| I <sub>OFF</sub>                          | power-off leakage current | V <sub>I</sub> or V <sub>O</sub> = 5.5 V; V <sub>CC</sub> = 0 V   | -                      | ±0.1               | ±10                    | μA   |
| I <sub>CC</sub>                           | supply current            | V <sub>I</sub> = 5.5 V or GND; I <sub>O</sub> = 0 A;<br>V <sub>CC</sub> = 1.65 V to 5.5 V                                 | -                      | 0.1                | 10                     | μA   |
| ΔI <sub>CC</sub>                          | additional supply current | per pin; V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A;<br>V <sub>CC</sub> = 2.3 V to 5.5 V              | <sup>[2]</sup> -       | 5                  | 500                    | μA   |
| C <sub>I</sub>                            | input capacitance         |   | -                      | 2.5                | -                      | pF   |

**Table 7.** Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol                                     | Parameter                 | Conditions  | Min                    | Typ <sup>[1]</sup> | Max                    | Unit |
|--|---------------------------|---|------------------------|--------------------|------------------------|------|
| <b>T<sub>amb</sub> = -40 °C to +125 °C</b> |                           |   |                        |                    |                        |      |
| V <sub>IH</sub>                            | HIGH-level input voltage  | V <sub>CC</sub> = 1.65 V to 1.95 V  | 0.65 × V <sub>CC</sub> | -                  | -                      | V    |
|  |                           | V <sub>CC</sub> = 2.3 V to 2.7 V  | 1.7                    | -                  | -                      | V    |
|  |                           | V <sub>CC</sub> = 2.7 V to 3.6 V  | 2.0                    | -                  | -                      | V    |
|  |                           | V <sub>CC</sub> = 4.5 V to 5.5 V  | 0.7 × V <sub>CC</sub>  | -                  | -                      | V    |
| V <sub>IL</sub>                            | LOW-level input voltage   | V <sub>CC</sub> = 1.65 V to 1.95 V  | -                      | -                  | 0.35 × V <sub>CC</sub> | V    |
|  |                           | V <sub>CC</sub> = 2.3 V to 2.7 V  | -                      | -                  | 0.7                    | V    |
|  |                           | V <sub>CC</sub> = 2.7 V to 3.6 V  | -                      | -                  | 0.8                    | V    |
|  |                           | V <sub>CC</sub> = 4.5 V to 5.5 V  | -                      | -                  | 0.3 × V <sub>CC</sub>  | V    |
| V <sub>OL</sub>                            | LOW-level output voltage  | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>   |                        |                    |                        |      |
|  |                           | I <sub>O</sub> = 100 μA; V <sub>CC</sub> = 1.65 V to 5.5 V  | -                      | -                  | 0.10                   | V    |
|  |                           | I <sub>O</sub> = 4 mA; V <sub>CC</sub> = 1.65 V   | -                      | -                  | 0.70                   | V    |
|  |                           | I <sub>O</sub> = 8 mA; V <sub>CC</sub> = 2.3 V  | -                      | -                  | 0.45                   | V    |
|  |                           | I <sub>O</sub> = 12 mA; V <sub>CC</sub> = 2.7 V   | -                      | -                  | 0.60                   | V    |
|  |                           | I <sub>O</sub> = 24 mA; V <sub>CC</sub> = 3.0 V   | -                      | -                  | 0.80                   | V    |
|  |                           | I <sub>O</sub> = 32 mA; V <sub>CC</sub> = 4.5 V   | -                      | -                  | 0.80                   | V    |
| I <sub>I</sub>                             | input leakage current     | V <sub>I</sub> = 5.5 V or GND;<br>V <sub>CC</sub> = 0 V to 5.5 V  | -                      | -                  | ±20                    | μA   |
| I <sub>OZ</sub>                            | OFF-state output current  | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND;<br>V <sub>CC</sub> = 5.5 V | -                      | -                  | ±10                    | μA   |
| I <sub>OFF</sub>                           | power-off leakage current | V <sub>I</sub> or V <sub>O</sub> = 5.5 V; V <sub>CC</sub> = 0 V   | -                      | -                  | ±20                    | μA   |
| I <sub>CC</sub>                            | supply current            | V <sub>I</sub> = 5.5 V or GND; I <sub>O</sub> = 0 A;<br>V <sub>CC</sub> = 1.65 V to 5.5 V                                 | -                      | -                  | 40                     | μA   |
| ΔI <sub>CC</sub>                           | additional supply current | per pin; V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A;<br>V <sub>CC</sub> = 2.3 V to 5.5 V              | -                      | -                  | 5000                   | μA   |

[1] All typical values are measured at T<sub>amb</sub> = 25 °C.[2] These typical values are measured at V<sub>CC</sub> = 3.3 V.

## 11. Dynamic characteristics

**Table 8. Dynamic characteristics**  
Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 8](#).

| Symbol          | Parameter                     | Conditions   | −40 °C to +85 °C |                    |     | −40 °C to +125 °C |     | Unit |
|-----------------|-------------------------------|--|------------------|--------------------|-----|-------------------|-----|------|
|                 |                               |  | Min              | Typ <sup>[1]</sup> | Max | Min               | Max |      |
| t <sub>pd</sub> | propagation delay             | nA to nY; see <a href="#">Figure 7</a> <sup>[2]</sup>                            |                  |                    |     |                   |     |      |
|                 |                               | V <sub>CC</sub> = 1.65 V to 1.95 V   | 1.0              | 3.2                | 6.5 | 1.0               | 8.2 | ns   |
|                 |                               | V <sub>CC</sub> = 2.3 V to 2.7 V   | 0.5              | 2.0                | 3.9 | 0.5               | 4.9 | ns   |
|                 |                               | V <sub>CC</sub> = 2.7 V  | 1.0              | 2.6                | 4.2 | 1.0               | 5.3 | ns   |
|                 |                               | V <sub>CC</sub> = 3.0 V to 3.6 V   | 0.5              | 2.3                | 3.4 | 0.5               | 4.3 | ns   |
|                 |                               | V <sub>CC</sub> = 4.5 V to 5.5 V   | 0.5              | 1.6                | 2.9 | 0.5               | 3.7 | ns   |
| C <sub>PD</sub> | power dissipation capacitance | V <sub>I</sub> = GND to V <sub>CC</sub> ; V <sub>CC</sub> = 3.3 V <sup>[3]</sup> | -                | 5.9                | -   | -                 | -   | pF   |

- [1] Typical values are measured at T<sub>amb</sub> = 25 °C and V<sub>CC</sub> = 1.8 V, 2.5 V, 2.7 V, 3.3 V and 5.0 V respectively.
- [2] t<sub>pd</sub> is the same as t<sub>PLZ</sub> and t<sub>PZL</sub>.
- [3] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$  where:  
f<sub>i</sub> = input frequency in MHz;  
f<sub>o</sub> = output frequency in MHz;  
C<sub>L</sub> = output load capacitance in pF;  
V<sub>CC</sub> = supply voltage in V;  
N = number of inputs switching;  
Σ(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of outputs.

## 12. Waveforms

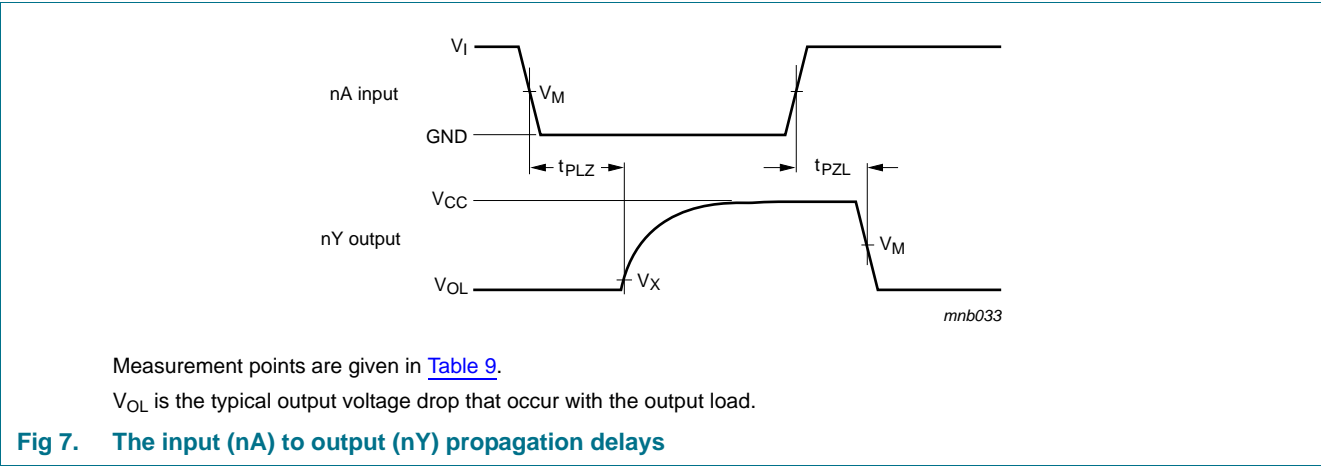
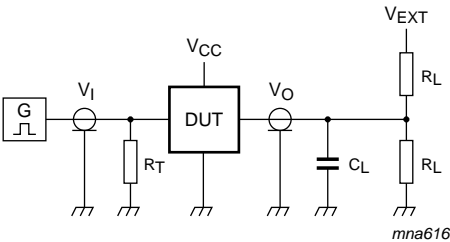


Table 9. Measurement points

| Supply voltage   | Input                 | Output                |                          |
|------------------|-----------------------|-----------------------|--------------------------|
| V <sub>CC</sub>  | V <sub>M</sub>        | V <sub>M</sub>        | V <sub>X</sub>           |
| 1.65 V to 1.95 V | 0.5 × V <sub>CC</sub> | 0.5 × V <sub>CC</sub> | V <sub>OL</sub> + 0.15 V |
| 2.3 V to 2.7 V   | 0.5 × V <sub>CC</sub> | 0.5 × V <sub>CC</sub> | V <sub>OL</sub> + 0.15 V |
| 2.7 V            | 1.5 V                 | 1.5 V                 | V <sub>OL</sub> + 0.3 V  |
| 3.0 V to 3.6 V   | 1.5 V                 | 1.5 V                 | V <sub>OL</sub> + 0.3 V  |
| 4.5 V to 5.5 V   | 0.5 × V <sub>CC</sub> | 0.5 × V <sub>CC</sub> | V <sub>OL</sub> + 0.3 V  |



Test data is given in [Table 10](#).  
Definitions for test circuit:  
R<sub>L</sub> = Load resistance.  
C<sub>L</sub> = Load capacitance including jig and probe capacitance.  
R<sub>T</sub> = Termination resistance should be equal to the output impedance Z<sub>o</sub> of the pulse generator.  
V<sub>EXT</sub> = External voltage for measuring switching times.

Fig 8. Test circuit for measuring switching times

Table 10. Test data

| Supply voltage   | Input           |                                 | Load           |                | V <sub>EXT</sub>                    |
|------------------|-----------------|---------------------------------|----------------|----------------|-------------------------------------|
| V <sub>CC</sub>  | V <sub>I</sub>  | t <sub>r</sub> , t <sub>f</sub> | C <sub>L</sub> | R <sub>L</sub> | t <sub>pZL</sub> , t <sub>pLZ</sub> |
| 1.65 V to 1.95 V | V <sub>CC</sub> | ≤ 2.0 ns                        | 30 pF          | 1 kΩ           | 2 × V <sub>CC</sub>                 |
| 2.3 V to 2.7 V   | V <sub>CC</sub> | ≤ 2.0 ns                        | 30 pF          | 500 Ω          | 2 × V <sub>CC</sub>                 |
| 2.7 V            | 2.7 V           | ≤ 2.5 ns                        | 50 pF          | 500 Ω          | 6 V                                 |
| 3.0 V to 3.6 V   | 2.7 V           | ≤ 2.5 ns                        | 50 pF          | 500 Ω          | 6 V                                 |
| 4.5 V to 5.5 V   | V <sub>CC</sub> | ≤ 2.5 ns                        | 50 pF          | 500 Ω          | 2 × V <sub>CC</sub>                 |

13. Package outline

Plastic surface-mounted package; 6 leadsSOT363

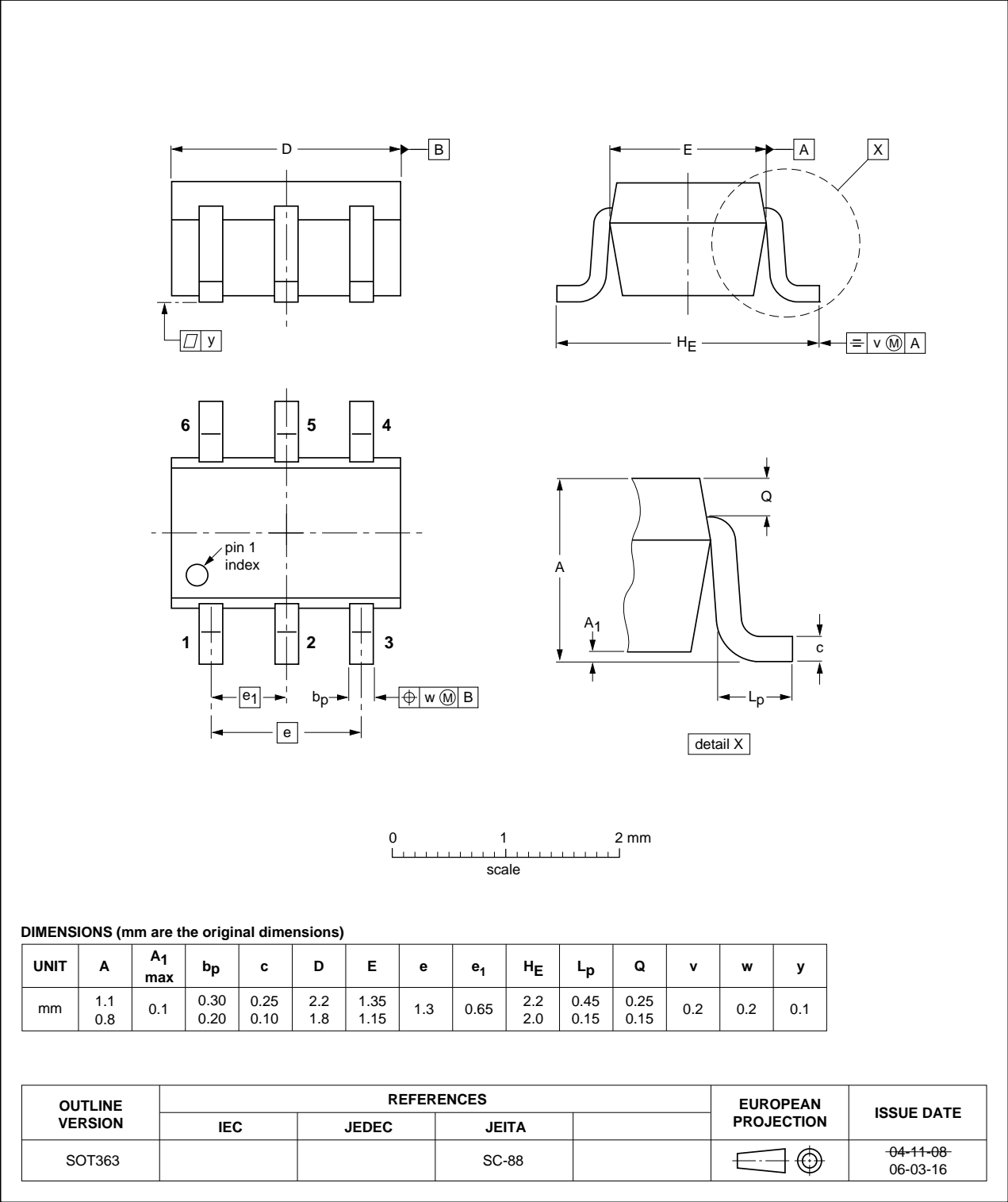


Fig 9. Package outline SOT363 (SC-88)

Plastic surface-mounted package (TSOP6); 6 leads

SOT457

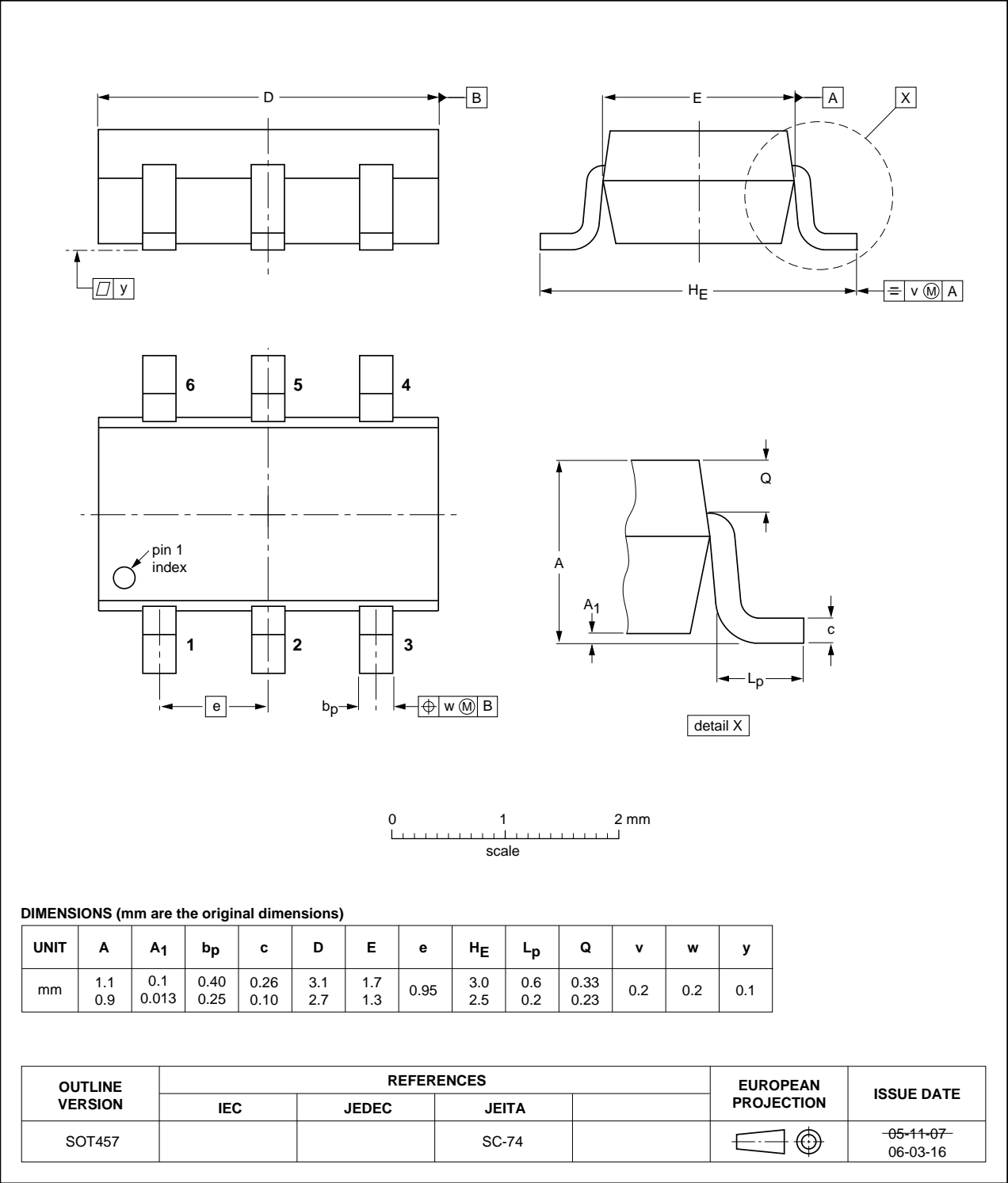


Fig 10. Package outline SOT457 (TSOP6)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

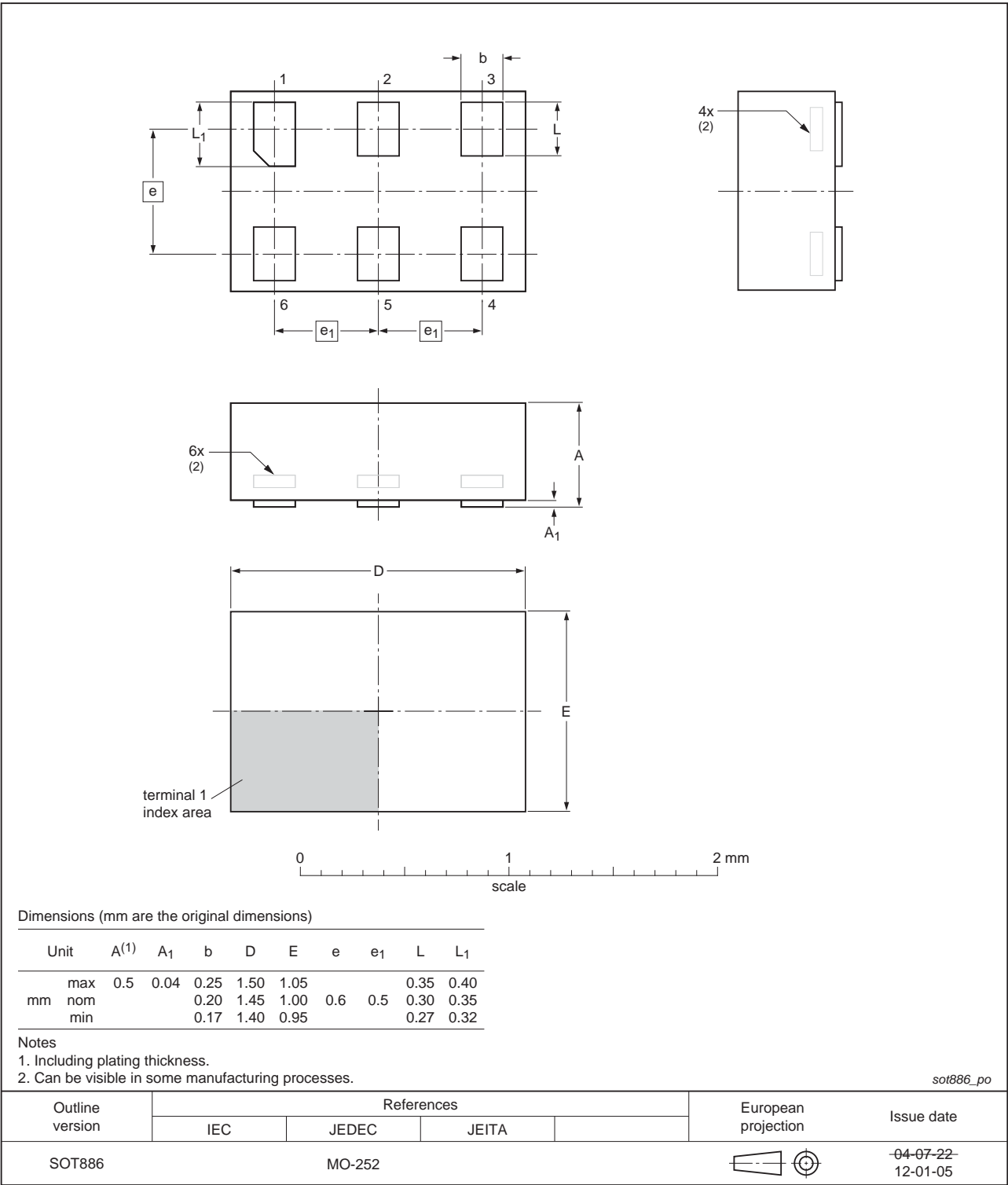


Fig 11. Package outline SOT886 (XSON6)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1 x 0.5 mm

SOT891

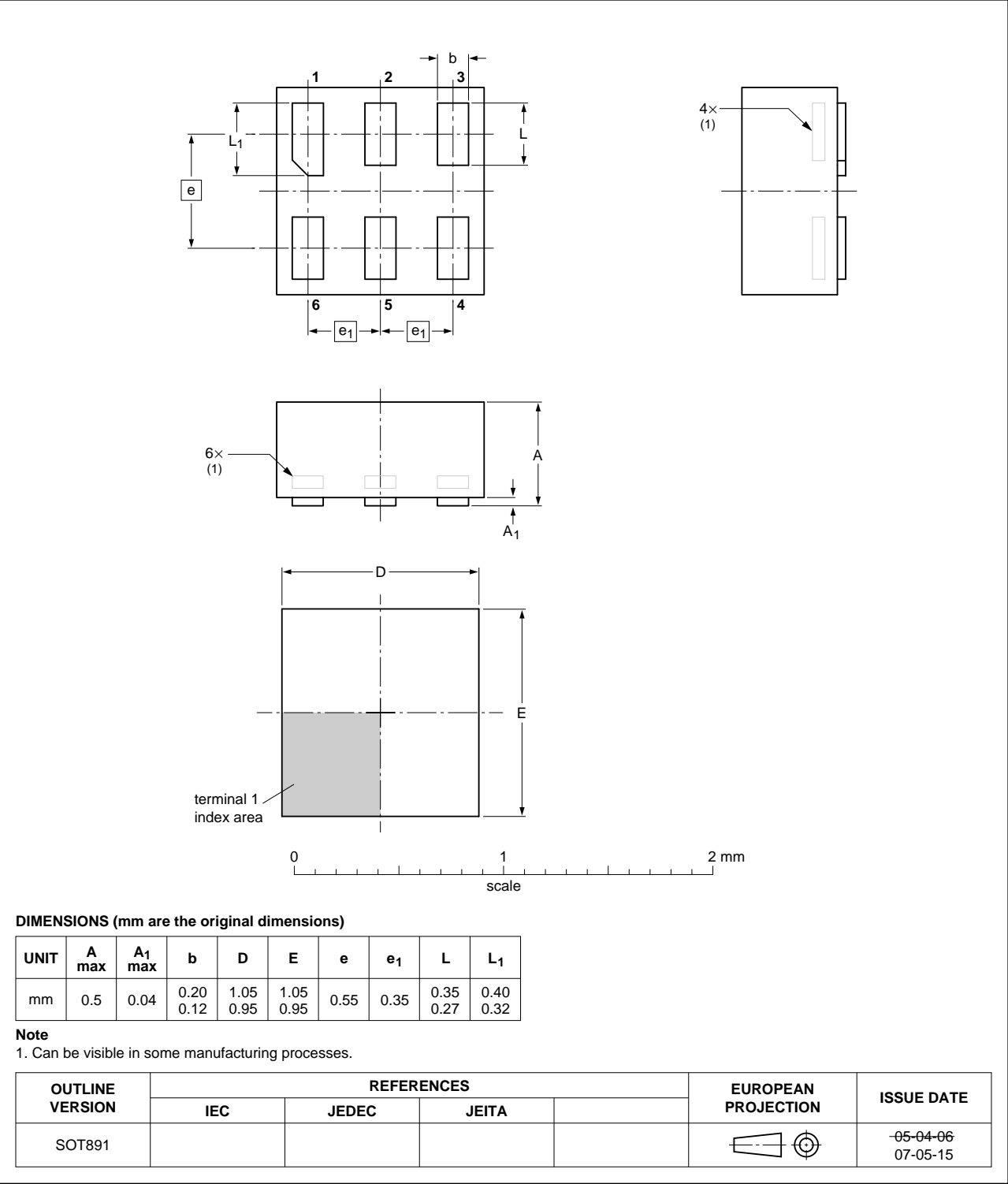
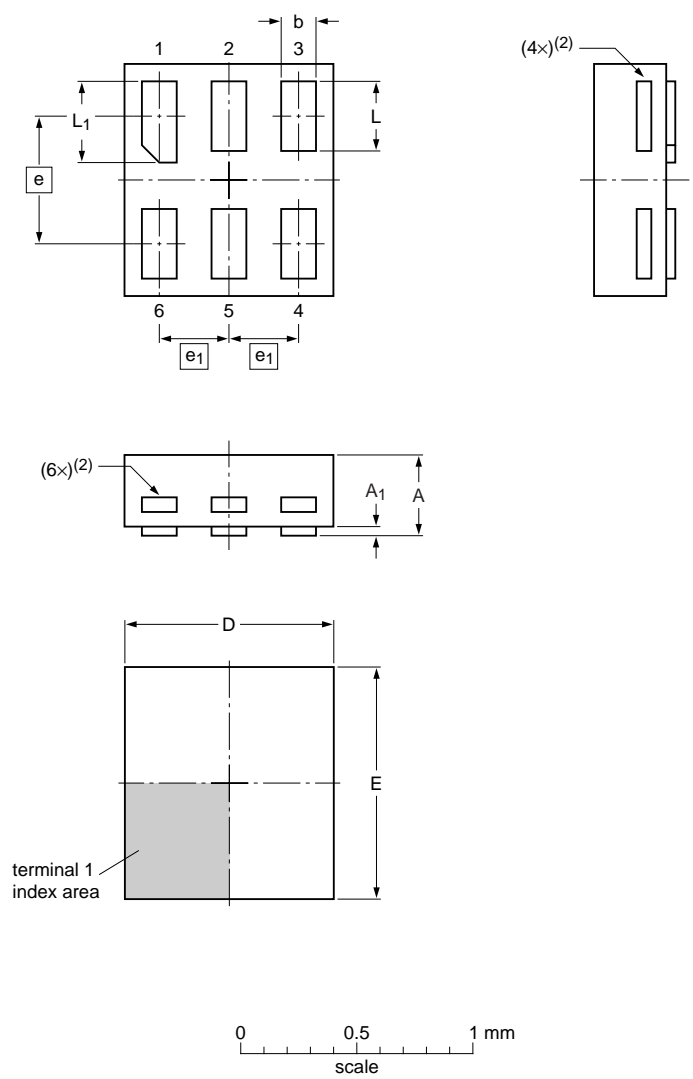


Fig 12. Package outline SOT891 (XSON6)

XSON6: extremely thin small outline package; no leads;  
6 terminals; body 0.9 x 1.0 x 0.35 mm

SOT1115



Dimensions

| Unit | A <sup>(1)</sup> | A <sub>1</sub> | b    | D    | E    | e    | e <sub>1</sub> | L    | L <sub>1</sub> |
|------|------------------|----------------|------|------|------|------|----------------|------|----------------|
| mm   | max              | 0.35           | 0.04 | 0.20 | 0.95 | 1.05 |                | 0.35 | 0.40           |
|      | nom              |                |      | 0.15 | 0.90 | 1.00 | 0.55           | 0.30 | 0.35           |
|      | min              |                |      | 0.12 | 0.85 | 0.95 |                | 0.27 | 0.32           |

Note

- 1. Including plating thickness.
- 2. Visible depending upon used manufacturing technology.

sot1115\_po

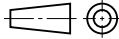
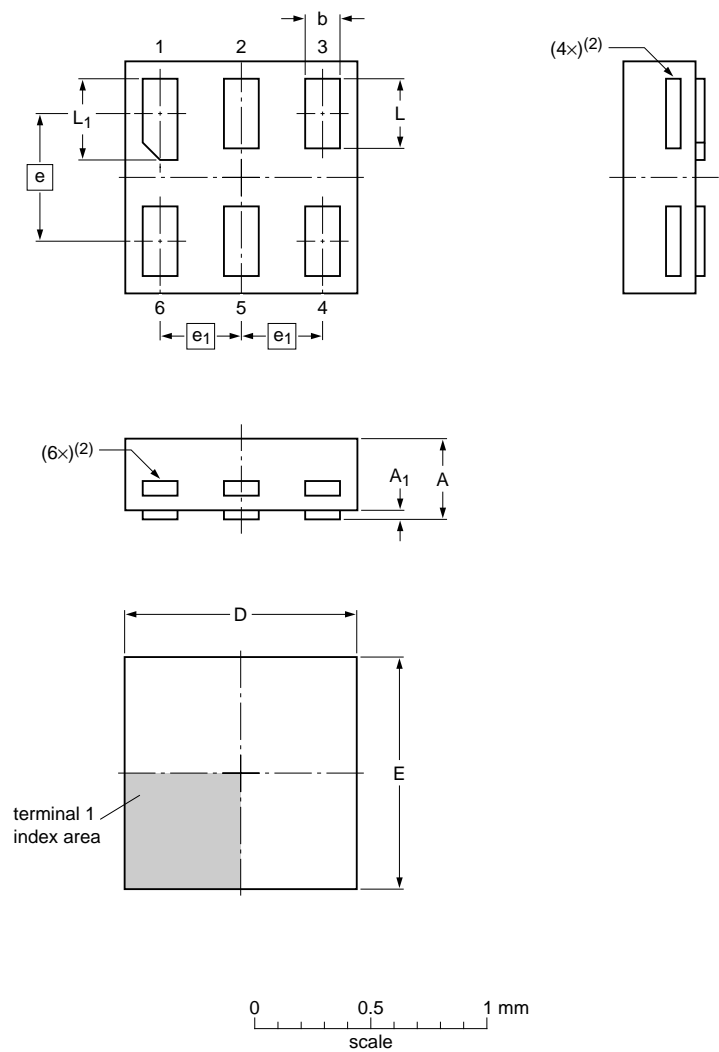
| Outline version | References |       |       |  | European projection   | Issue date                      |
|-----------------|------------|-------|-------|--|---|---------------------------------|
|                 | IEC        | JEDEC | JEITA |  |   |                                 |
| SOT1115         |            |       |       |  |  | <del>10-04-02</del><br>10-04-07 |

Fig 13. Package outline SOT1115 (XSON6)

XSON6: extremely thin small outline package; no leads;  
6 terminals; body 1.0 x 1.0 x 0.35 mm

SOT1202



Dimensions

| Unit | A <sup>(1)</sup> | A <sub>1</sub> | b    | D    | E    | e    | e <sub>1</sub> | L    | L <sub>1</sub> |
|------|------------------|----------------|------|------|------|------|----------------|------|----------------|
| mm   | max              | 0.35           | 0.04 | 0.20 | 1.05 | 1.05 |                | 0.35 | 0.40           |
|      | nom              |                |      | 0.15 | 1.00 | 1.00 | 0.55           | 0.30 | 0.35           |
|      | min              |                |      | 0.12 | 0.95 | 0.95 |                | 0.27 | 0.32           |

Note

- 1. Including plating thickness.
- 2. Visible depending upon used manufacturing technology.

sot1202\_po

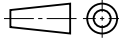
| Outline version | References |       |       |  | European projection   | Issue date                      |
|-----------------|------------|-------|-------|--|---|---------------------------------|
|                 | IEC        | JEDEC | JEITA |  |   |                                 |
| SOT1202         |            |       |       |  |  | <del>10-04-02</del><br>10-04-06 |

Fig 14. Package outline SOT1202 (XSON6)

## 14. Abbreviations

Table 11. Abbreviations

| Acronym | Description                             |
|---------|---|
| CMOS    | Complementary Metal Oxide Semiconductor |
| DUT     | Device Under Test                       |
| ESD     | ElectroStatic Discharge                 |
| HBM     | Human Body Model                        |
| MM      | Machine Model                           |
| TTL     | Transistor-Transistor Logic             |

## 15. Revision history

Table 12. Revision history

| Document ID    | Release date  | Data sheet status     | Change notice | Supersedes    |
|----------------|---|-----------------------|---------------|---------------|
| 74LVC2G06 v.6  | 20120704  | Product data sheet    | -             | 74LVC2G06 v.5 |
| Modifications: | • Package outline drawing of SOT886 ( <a href="#">Figure 11</a> ) modified. |                       |               |               |
| 74LVC2G06 v.5  | 20111130  | Product data sheet    | -             | 74LVC2G06 v.4 |
| Modifications: | • Legal pages updated.  |                       |               |               |
| 74LVC2G06 v.4  | 20101028  | Product data sheet    | -             | 74LVC2G06 v.3 |
| 74LVC2G06 v.3  | 20070521  | Product data sheet    | -             | 74LVC2G06 v.2 |
| 74LVC2G06 v.2  | 20040910  | Product specification | -             | 74LVC2G06 v.1 |
| 74LVC2G06 v.1  | 20030825  | Product specification | -             | -             |

## 16. Legal information

### 16.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition  |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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